

CLASS II FABRICATION NOTES: (UNLESS OTHERWISE SPECIFIED)

1. BOARDS SHALL BE 100% NET LIST TESTED FOR OPENS AND SHORTS PER PROVIDED IPC-D-356 NETLIST.

2. THIS BOARD SHALL BE MANUFACTURED IN ACCORDANCE WITH IPC-6012A CLASS II SPECIFICATIONS AND MEET IPC-600 CLASS II ACCEPTABILITY STANDARDS.

3. MATERIAL:

a. FR4 PER IPC 4101B/24 /26, OR /28.

b. SIGNAL LAYERS TO BE 2 OZ. COPPER.

c. OVERALL THICKNESS TO BE 0.062" +/- 0.003"

4. LEGEND:

a. WHITE NON-CONDUCTIVE EPOXY INK BOTH SIDES.

5. SOLDERMASK:

a. APPLY LIQUID PHOTO-IMAGABLE (LPI) SOLDER MASK OVER BARE COPPER PER IPC-SM-840 CLASS H, COLOR GREEN, BOTH SIDES.

6. PLATING FINISH:

a. HOT AIR SOLDER LEVELING (HASL) SN63A SnPb SOLDER.

7. PROCESS ALLOWANCES:

a. MAXIMUM BOW AND TWIST ACROSS DIAGONAL CORNERS OF THE BOARD SHALL NOT EXCEED 0.75%.

b. HOLE DIMENSIONS APPLY AFTER PLATING.

c. ALL HOLES SHALL BE LOCATED WITHIN 0.003" DIAMETER OF TRUE POSITION.

d. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003".

e. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- 0.002".

f. REMOVE ALL BURRS AND BREAK SHARP EDGES 0/015" MAX.

g. CUT OUTSIDE OF 0.001" BOARD OUTLINE.

REVISIONS

REV	DESCRIPTION	DATE	APPROVED

126

T55

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126

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126

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126

DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS

FIGURE	SIZE	PLATED	QTY
T50	50.0	PLATED	9
T55	55.0	PLATED	11
T63	63.0	PLATED	2
T67	67.0	PLATED	18
126	126.0	PLATED	4

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	CAMERA TRIPOD DIODE BOARD			
DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS +/- 0.02" 3 PL DECIMALS +/- 0.005" ANGLES +/- 1 Degree FRACTIONS +			MONTEREY BAY AQUARIUM RESEARCH INSTITUTE 7700 SANDHOLDT ROAD MOSS LANDING, CA			
			SIZE B	REVISION 0-0	DWG NO 10020482	
	DESIGNED BY: ALANA SHERMAN					
	LAYOUT BY: JOSE ROSAL		SCALE 1 - 1		SHEET 1 - 1	